

DuPont™ EKC1020™

Negative Resist Remover

Product Description

DuPont™ EKC1020™ negative resist remover contains no phenol or chlorinated solvents and will remove photoresist without attack of conventional interconnect materials, copper, or polyimide films.

Typical applications for EKC1020™ include integrated circuits, backlap cleaning, chrome photomasks, s. These products can also be used to remove epoxy inks and backlap way, acrylic adhesives as well as grease, oils and other organics from glassware.

DuPont™ EKC1020™ is specifically formulated to remove negative photoresist and to be compatible with sensitive metals where corrosion is a concern.

Performance Characteristics

Strip Time and Temperature

EKC1020™ strips negative and positive resist in 10 to 20 minutes under normal circumstances when heated to $105\text{ }^{\circ}\text{C} \pm 5\text{ }^{\circ}\text{C}$. For best results, two baths in sequence are preferred. The operating temperature of the stripper and process time may need to be adjusted to accommodate individual needs. Contact your DuPont EKC technical representative for specific process recommendations.

Bath Life

EKC1020™ typically lasts eight hours at elevated temperatures in an uncovered bath. Longer bath life can be achieved by covering the bath.

High Wafer Throughput

EKC1020™ will strip 700-1000 wafers per setup. Throughput will vary according to wafer size, resist thickness and percent of coverage.





ekctech.dupont.com

For more information on DuPont™ EKC1020™ or other DuPont products, please visit our website.

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CAUTION: Do not use in medical applications involving permanent implantation in the human body. For other medical applications, see "DuPont Medical Caution Statement," H-50102-5 and "DuPont Policy Regarding Medical Applications" H-50103-5.

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